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**Guidance for the Development and
Implementation of a Foreign
Object Debris (FOD) Control Plan**

A White Paper Report Developed by IPC

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- Focus on end product performance
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Guidance for the Development and Implementation of a Foreign Object Debris (FOD) Control Plan

Developed by the Wire Harness Design Task Group (7-31k)
and IPC-HDBK-620 Handbook Task Group (7-31h) of the
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Users of this publication are encouraged to participate in the
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